

Notice of References Cited	Application/Control No. 10/619,738		Applicant(s)/Patent Under Reexamination ANNAMANENI ET AL.	
	Examiner Carlos Ortiz-Rodriguez		Art Unit 2125	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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*	B	US-5,841,660	11-1998	Robinson et al.	700/115
*	C	US-5,889,674	03-1999	Burdick et al.	700/121
*	D	US-6,684,121	01-2004	Lu et al.	700/108
*	E	US-6,748,287	06-2004	Hagen et al.	700/99
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*	I	US-7,006,885	02-2006	Chen, Yen-Hung	700/102
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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
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	V	"Oracle E-Business Suite High-Tech Semiconductor Industry Solution, Key SCM Challenges and Oracle's Strategy/Response", An Oracle White Paper, February 2003.
	W	"A framework for supply chain management in semiconductor manufacturing industry", to Ovacik et al., i2 Technologies, 1995 IEEE.
	X	"eSilicon Delivers ASIC Time to market breakthrough; fables ASIC Company Announces Infrastructure to speed design, manufacture, and delivery of chips", Business Wire, July 24, 2001.

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.